

Supporting Information for

Vertically Aligned Silicon Carbide Nanowires/Boron Nitride Cellulose Aerogel Networks Enhanced Thermal Conductivity and Electromagnetic Absorbing of Epoxy Composites

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Supplementary Figures

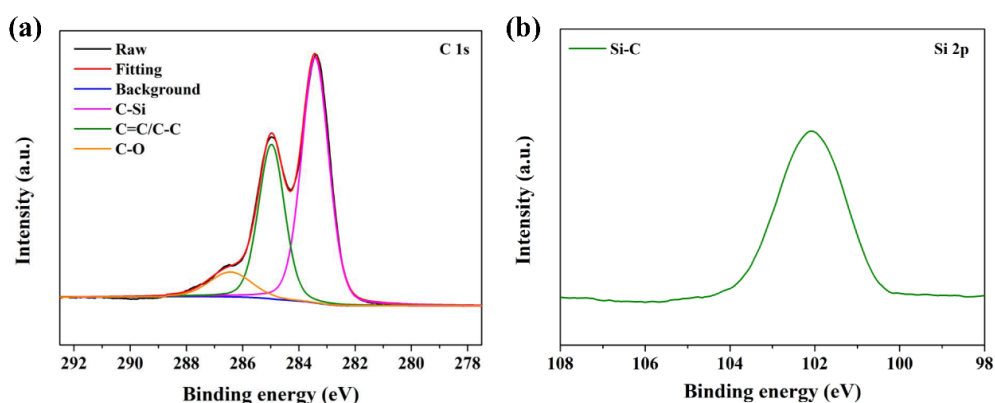


Fig. S1 High-resolution XPS analysis of **a** C 1s and **b** Si 2p of commercial SiC NWs

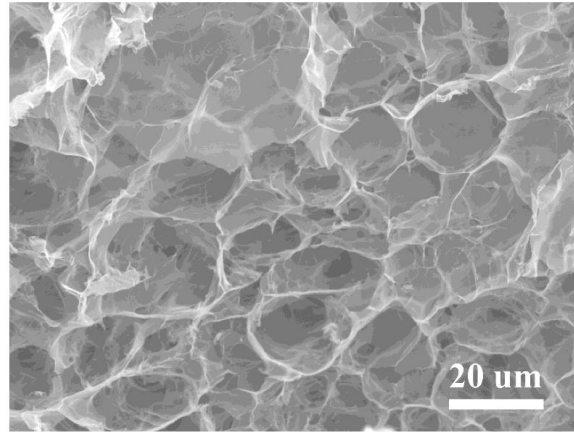


Fig. S2 SEM image of CA

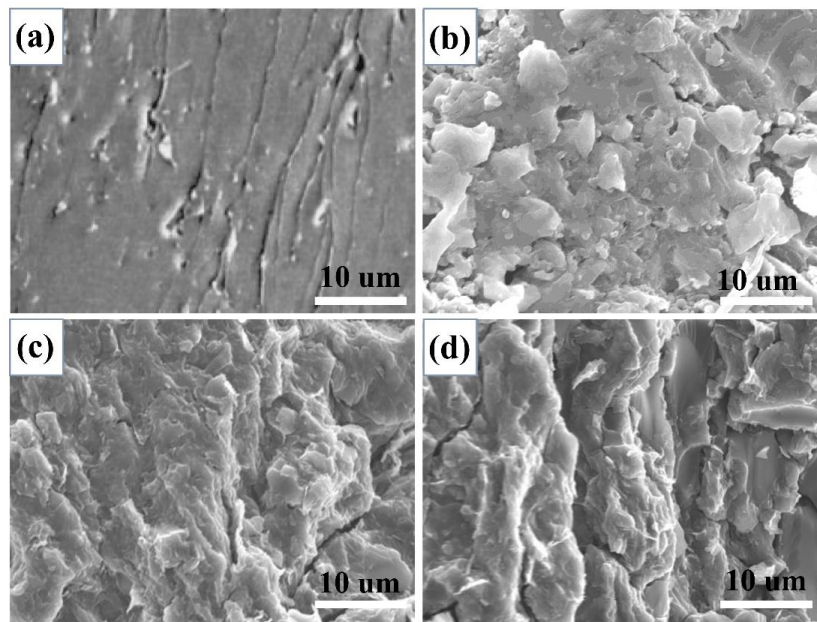


Fig. S3 SEM images of **a** CA/0.10m-SiC/EP, **b** CA/1.8m-BN/EP, **c** CA/0.10m-SiC/1.8m-BN/EP_{blend} and **d** CA/0.10m-SiC/1.8m-BN/EP

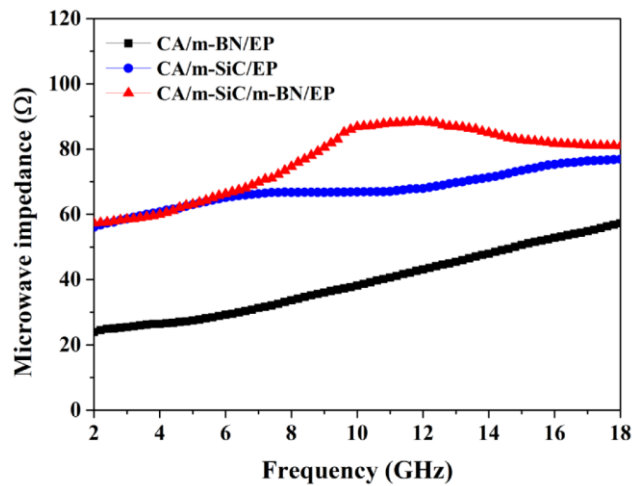


Fig. S4 The microwave impedance of CA/m-SiC/EP, CA/m-BN/EP and CA/m-SiC/m-BN/EP
Calculation process of filler content

Since the sample presents a regular cylinder, the density is measured according to the following Equation (S1):

$$\sigma = \frac{m}{V} \quad (S1)$$

where σ , m and V are the density, mass and volume of the different samples, respectively.

The filler content is obtained with the help of a thermal gravimetric analyzer. Since BN and SiC are both thermally stable materials with high temperature resistance, ignoring the small effects of surface adsorbed water and modified groups, the total filler loading is referred to Equation (S2):

$$\vartheta = \frac{m'}{m_0} \times 100\% \quad (S2)$$

where ϑ is the weight fraction of total filler, m_0 is the mass of the sample before testing, m' is the mass of the sample after the thermal analysis test at air atmosphere in 600 °C. So, the m-SiC NWs loading is obtained by Equation (S3):

$$\epsilon = \vartheta \times \frac{x}{x+y} \times 100\% \quad (S3)$$

And, the m-BN loading is obtained by Equation (S4):

$$\varphi = \vartheta \times \frac{y}{x+y} \times 100\% \quad (S4)$$

where ϵ and x are the mass content of m-SiC NWs and the mass added during sample synthesis, respectively; φ and y are the mass content of m-BN and the mass added during sample synthesis, respectively.

Table S1 The density of CA/m-SiC/m-BN/EP composites with different m-SiC NWs contents at the m-BN mass of 1.8 g, and the corresponding filler loadings

Samples	Density (g cm ⁻³)	m-SiC NWs (wt%)	m-BN (wt%)	Filler loading (wt%)
CA/1.8m-BN/EP	1.145	0.00	14.37	14.37
CA/0.03m-SiC/1.8m-BN/EP	1.116	0.24	14.42	14.66
CA/0.06m-SiC/1.8m-BN/EP	1.083	0.50	14.89	15.39
CA/0.10m-SiC/1.8m-BN/EP	1.032	0.88	15.81	16.69
CA/0.13m-SiC/1.8m-BN/EP	0.958	1.25	17.25	18.50

Table S2 The density of CA/m-SiC/m-BN/EP composites with different m-BN contents at the m-SiC NWs mass of 0.10 g, and the corresponding filler loadings

Samples	Density (g cm ⁻³)	m-SiC NWs (wt%)	m-BN (wt%)	Filler loading (wt%)
CA/0.10m-SiC/EP	0.732	0.74	0.00	0.74
CA/0.10m-SiC/0.5m-BN/EP	0.841	0.81	4.03	4.84
CA/0.10m-SiC/1.0m-BN/EP	0.927	0.82	8.20	9.02
CA/0.10m-SiC/1.5m-BN/EP	0.989	0.87	13.04	13.91
CA/0.10m-SiC/1.8m-BN/EP	1.032	0.88	15.81	16.69

Table S3 A comparison of the *TC* of the bulk composites reported in some recent literatures

Composites	Filler content	<i>K</i> (W/mK)	Refs.
AlN/C/EP	12.4 wt%	0.49	2022 [S1]
BN/PVMQ	31 vol%	1.64	2022 [S2]
CNTs/PP@Gr	CNTs 2wt% Gr 13.01wt%	0.82	2022 [S3]
ND@SCNWs/PDMS	25 wt%	0.57	2022 [S4]
PEEK/MWCNT/GNS	MWCNT 5wt% GNS 20wt%	2.64	2022 [S5]
BN-rGO/NR	12 wt%	1.04	2022 [S6]
BN/MXene/PVA	44 wt%	1.51	2021 [S7]
QAC/BN/PP	10 wt%	0.88	2021 [S8]
Al ₂ O ₃ /EP	17.7 wt%	0.72	2021 [S9]
BN@AgNWs/PDMS	20 vol%	0.91	2021 [S10]
EVA@BN/EP	16.8 vol%	1.85	2021 [S11]
BN/CNTs/TPU	65 wt%	1.35	2020 [S12]
BN@CNTs/PBz	25 wt%	0.79	2020 [S13]
BNNS/PDMS	35 wt%	1.16	2020 [S14]
BN/Fe ₃ O ₄ /EP	20 wt%	1.07	2020 [S15]
CA/m-SiC/m-BN/EP	16.69 wt%	2.21	This work

Notes: AlN: Aluminum Nitride, PVMQ: phenyl silicone rubber, CNTs: carbon nanotubes, PP: polypropylene, Gr: Graphite, ND: nano-crystalline diamonds, SCNWs: SiC nanowires, PDMS: polydimethylsiloxane, PEEK: poly (ether ether ketone), MWCNT: multi-walled carbon nanotube, GNS: graphite nanosheet, rGO: reduced graphene oxide, NR: natural rubber, PVA: Poly(Vinyl Alcohol), QAC: Quaternary ammonium salt, EVA: poly (ethylene-co-vinylacetate), TPU: polyurethane, PBz: polybenzoxazine.

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